

Application number

1376031

Registration number

TMA759608

Type(s)

Word

Category

Trademark

CIPO Status

REGISTERED

TM5 status

LIVE/REGISTRATION/Issued
and Active



The trademark application has
been registered with the Office.

Filed

2007-12-14

Registered

2010-02-16

Registration Expiry Date

2035-02-16

Registered Owner

Taiwan Semiconductor
Manufacturing Co., Ltd.
No. 8, Li-Hsin Road 6
Hsinchu Science Park
Hsinchu, 300096
Taiwan
CHINA

Agent

SMART & BIGGAR LP
Scotia Plaza, 40 King Street
West
40th Floor
Toronto
ONTARIO M5H3Y2

Documents

Index headings

TSMC

Goods (Nice class & Statement)

- 9 (1) Semiconductor integrated circuit; wafer of integrated circuit; masks for integrated circuits; masks, namely, integrated circuit topographies; pre-recorded data storage carriers, namely, floppy disk, compact disk, digital versatile disk, hard disks laserdiscs optical discs, CD-ROM, memory chip and tape, storing the database of information relating to integrated circuit process equipment and devices and information relating to semiconductor chip process technology and devices; pre-recorded data storage carriers, namely, floppy disk, compact disk, digital versatile disk, hard disks laserdiscs optical discs, CD-ROM, memory chip and tape for storing computer software for designing integrated circuit process technology, device and circuitry; computer software for designing and establishing the database of design device and process technology for integrated circuit; computer software for integrated circuit design; semiconductor chip for data accessing in the database of semiconductor wafer process equipment; semiconductor chip for data accessing in the database of integrated circuit design device and integrated circuit processing technology;
- 16 (2) Books, brochures, instruction manuals and periodicals in relation to semiconductor fabrication and processing techniques.

Services (Nice class & Statement)

- 35 (1) Retailing and wholesaling of semiconductors, wafers (silicon slices), integrated circuits and semiconductor processing equipment; provision of retailing and distributorship information in relation to semiconductors, wafers (silicon slices), integrated circuits and semiconductor processing equipment; providing business information, namely, technical and engineering information related to semiconductor wafer process equipment, integrated circuit design, integrated circuit processing technology and semiconductor chip processing technology; providing business information relating to integrated circuit design, integrated circuit processing technology and semiconductor chip processing technology; provision of business information relating to purchasing of semiconductors and integrated circuits through the global communication network;
- 40 (2) Fabrication and processing of semiconductors, wafers (silicon slices) and integrated circuits in accordance with the customers' instructions; custom assembling and sealing of semiconductors, wafers (silicon slices) and integrated circuits for others; cutting of semiconductor wafers (silicon slices) and integrated circuits; etching of

- semiconductor wafers (silicon slices) and integrated circuits; assembling of integrated circuits, protective masks and electronic or computer chips for customers; providing information relating to custom manufacturing of semiconductors and integrated circuits through the global communication network;
- 41 (3) Organizing and conducting of seminars, lectures or symposiums relating to the technique and equipment of semiconductors, wafers (silicon slices) and integrated circuits;
- 42 (4) Providing engineering and design services regarding semiconductor integrated circuit design, development and technology consultation through a global communication network; providing information regarding semiconductor integrated circuit design and development to customer's order; providing consulting services for integrated circuit design; integrated circuit mask and topography design services; providing lease, supply, design, development, modification, establishing, analysis, consultation, access, time-measuring, management, design and compiling, as well as coordinating and planning for the database of semiconductor process equipment, integrated circuit design device and process technology; technology development and system analysis of program designing and development for the database of semiconductor chip process equipment, integrated circuit design device and process technology; providing design service for semiconductor wafer via the global internet connection; providing software data for designing the integrated circuit process technology, device and circuitry via the global internet connection; testing service for masks, namely, integrated circuit masks and integrated circuit topographies, and integrated circuits and electronic chips.
- 45 (5) Licensing agency services for licensing the use of databases for semiconductor chip process equipment, integrated circuit design device and integrated circuit usage.

Claims

Declaration of Use filed February 01, 2010

Recordals (known also as Footnotes)

CHANGE IN TITLE / CHANGEMENT EN TITRE:

TYPE OF CHANGE / GENRE DE CHANGEMENT: Name and Address / Nom et adresse

DATE REGISTERED / DATE DE L'ENREGISTREMENT: 2021-09-17

DATE OF CHANGE / DATE DE CHANGEMENT: 2021-09-17

COMMENTS / COMMENTAIRES: FROM: TAIWAN SEMICONDUCTOR MANUFACTURING COMPANY LIMITED

a legal entity

TO: Taiwan Semiconductor Manufacturing Co., Ltd.

Voir Preuve au dossier/See evidence on File No. 1376031

Action History

Action	Action date	Due date	Comments

Filed	2007-12-14		
Created	2007-12-14		
Formalized	2007-12-19		
Search Recorded	2008-07-28		
Examiner's First Report	2008-09-08	2009-01-08	
Extension of Time	2009-01-20	2009-07-08	Request Letter Date: 2009 /01/05
Approval Notice Sent	2009-02-24	2009-03-24	
Approved	2009-04-16		APPROVED BY PROGRAM EX200M1
Advertised	2009-04-22		Vol.56 Issue 2843
Allowance Notice Sent	2009-08-07	2010-12-14	
Allowed	2009-08-07		
Registered	2010-02-16	2025-02-16	
Amendment to Registration	2021-09-17		Name and Address / Voir Preuve au dossier/See evidence on File No. 1376031
Agent Changed	2021-09-17		From: 6489 To: 2502 / Voir Preuve au dossier/See evidence on File No. 1376031
Adjusted Renewal Fee Received	2024-08-30		
Nice Class(es) Acceptance Letter Sent	2024-12-05		
Renewed	2025-02-16	2035-02-16	DP:2024/08/30 RD:2024/08 /30 RR:(2502) BERESKIN & PARR LLP/S.E.N.C.R.L., S.R.L.
Agent Changed	2026-04-21		Transferred From: 2502 To: 59